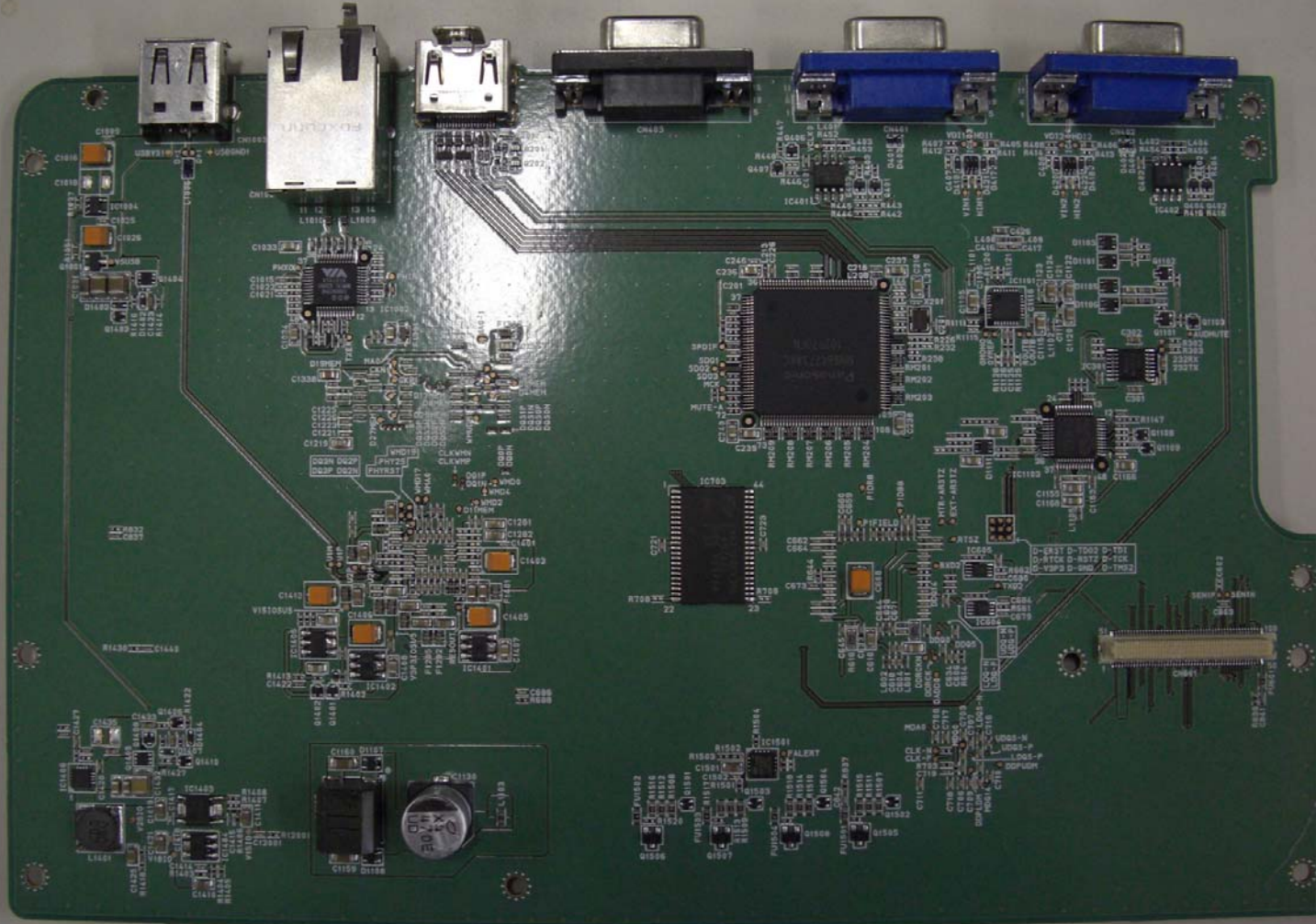


Change list

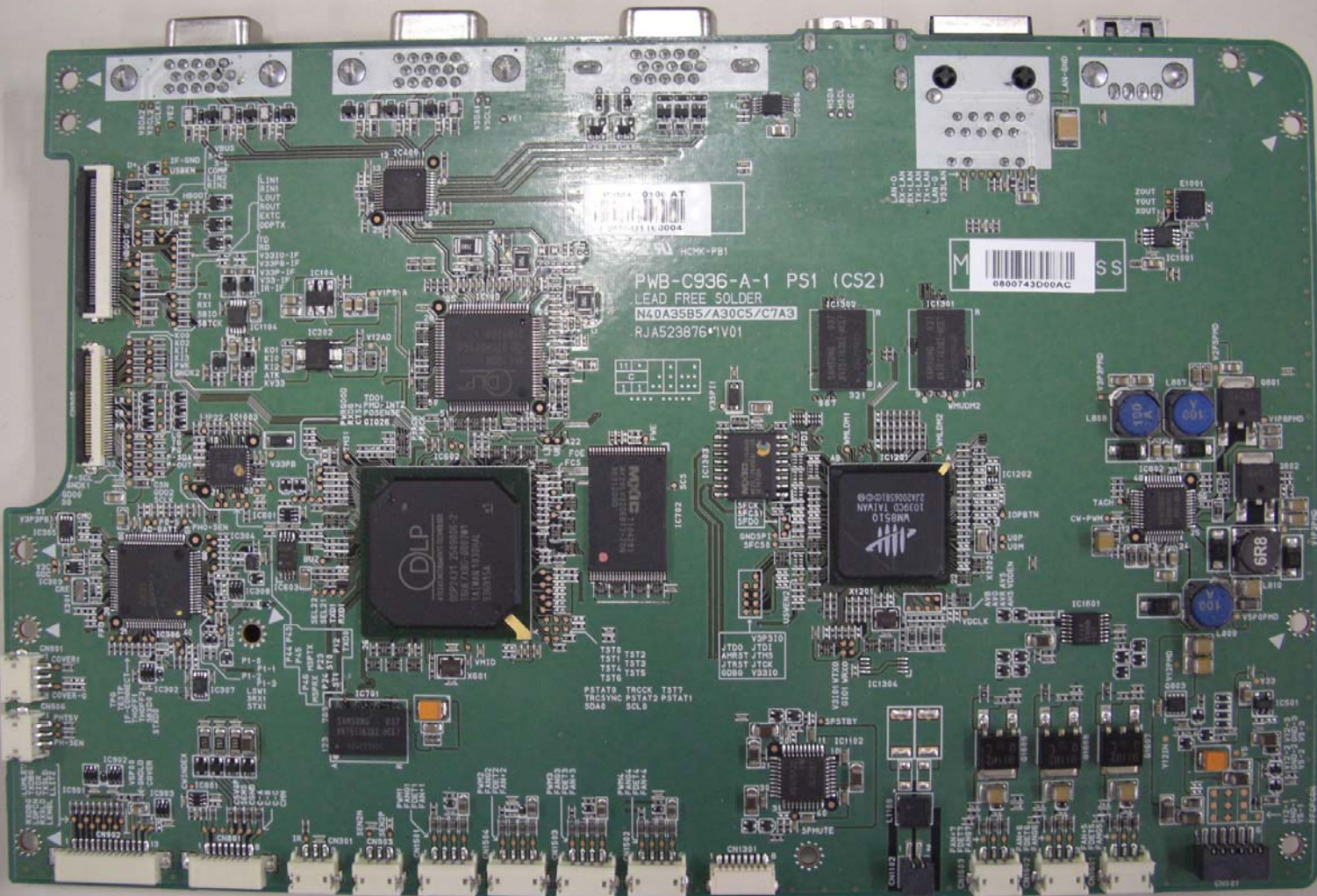
Differnce				
item	change	XJ-H1750	XJ-H2650	Notes
Optical Mainfold Digital Mirror Device	Applly	for XGA	for WXGA	Change of the Digital Mirror Device for Optical Manifold
Main PWB	Applly	number of layer 8 layer	number of layers 6 layers	Altered the printed wiring and number of layers. Supports the RGB-function of the Stand-By State. Addition of the Line-OUT port.
PWB for Key	Nothing	Same		
RF Module				
others				

Internal Photo

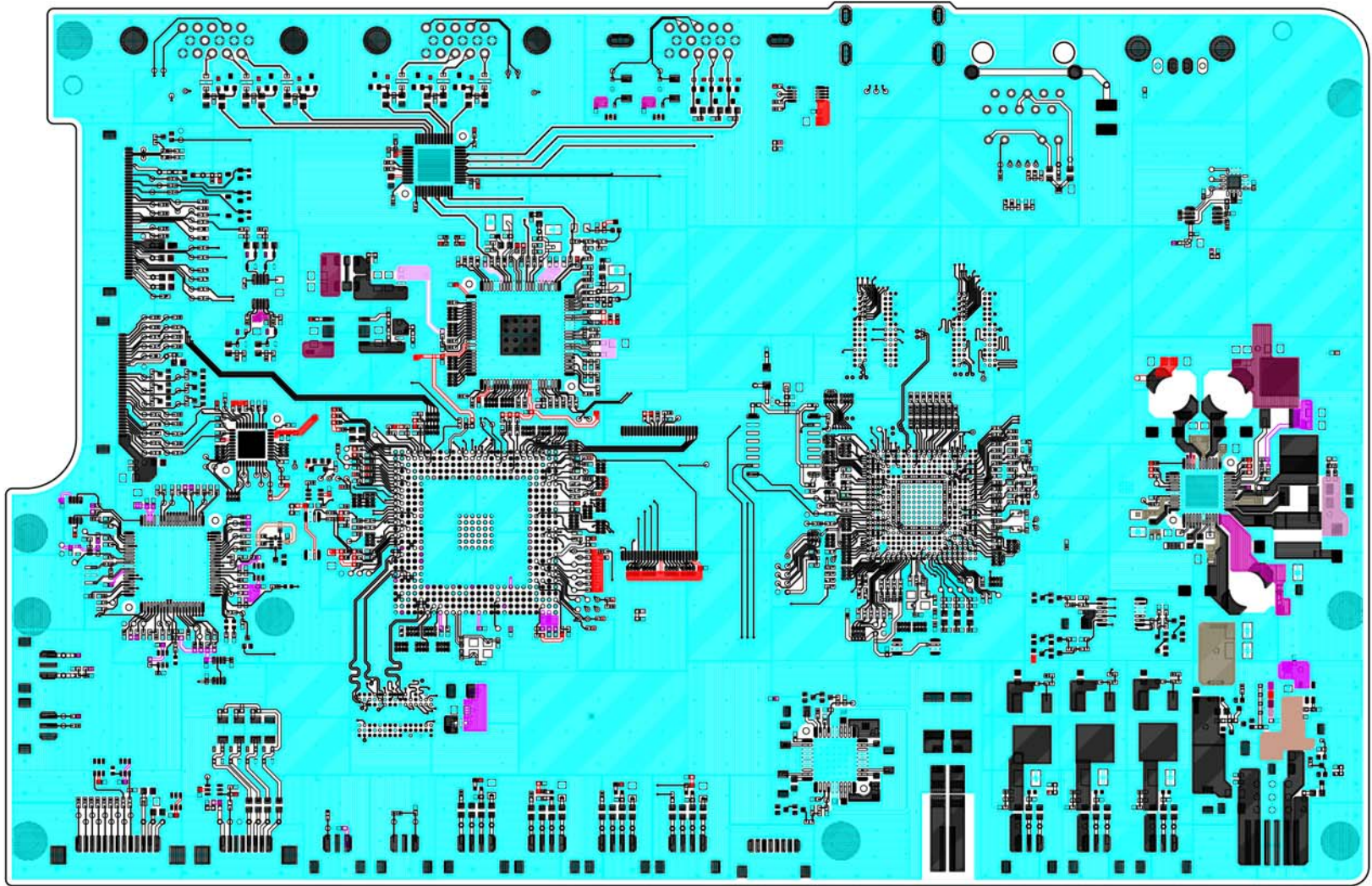


Main board(XJ-H1750) Upper Before

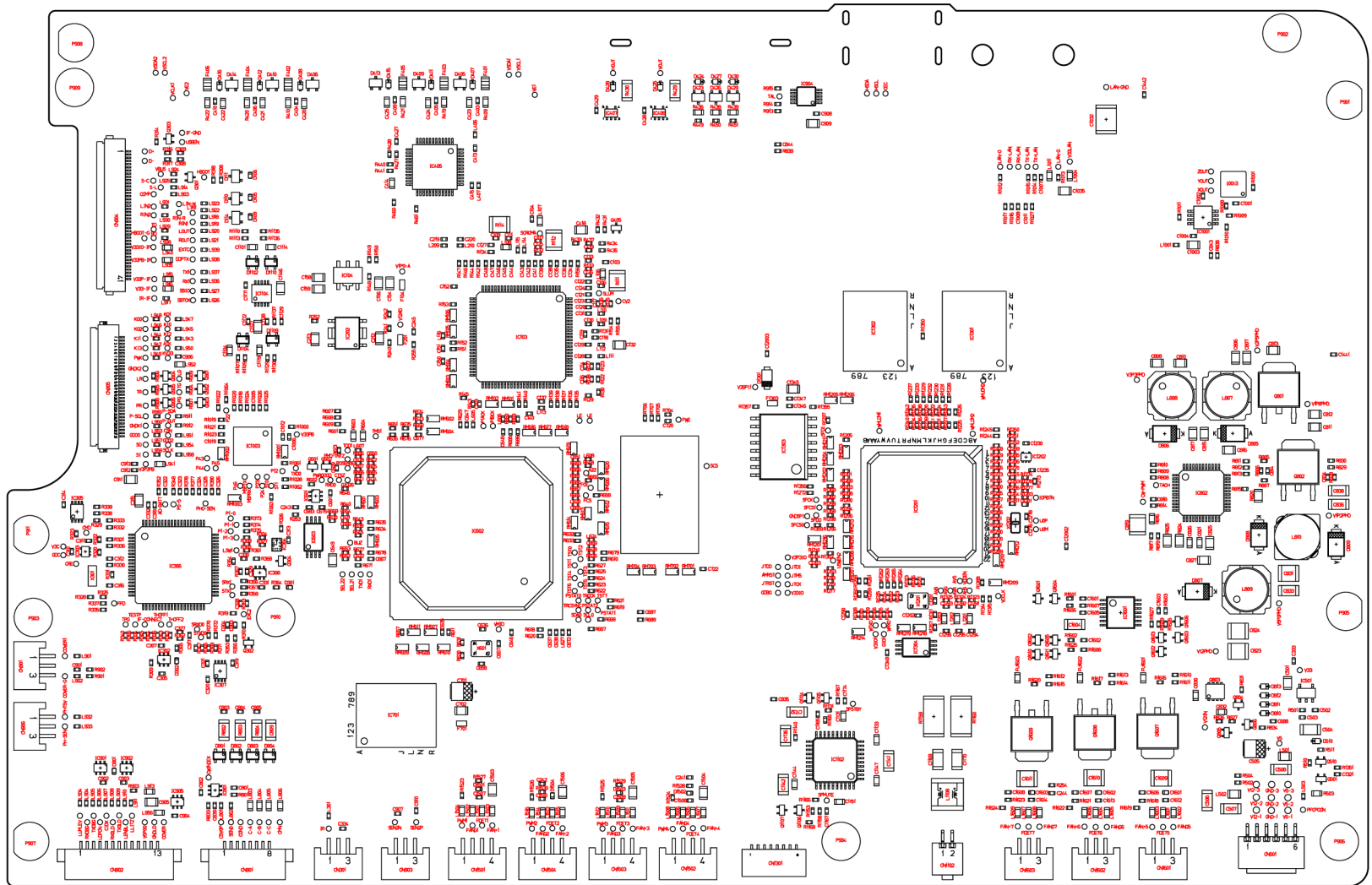
Internal Photo



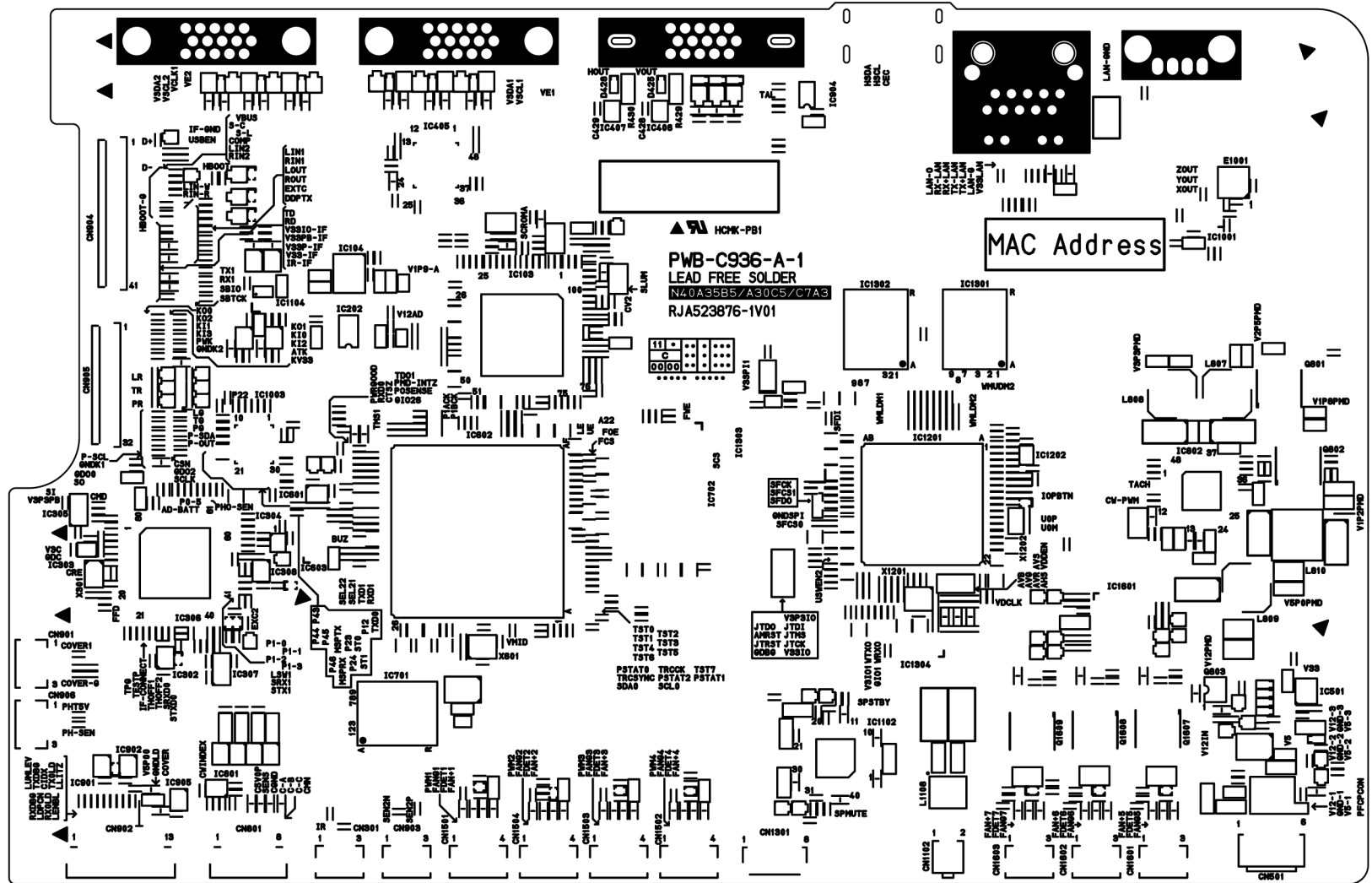
Main board(XJ-H1750) Under Before



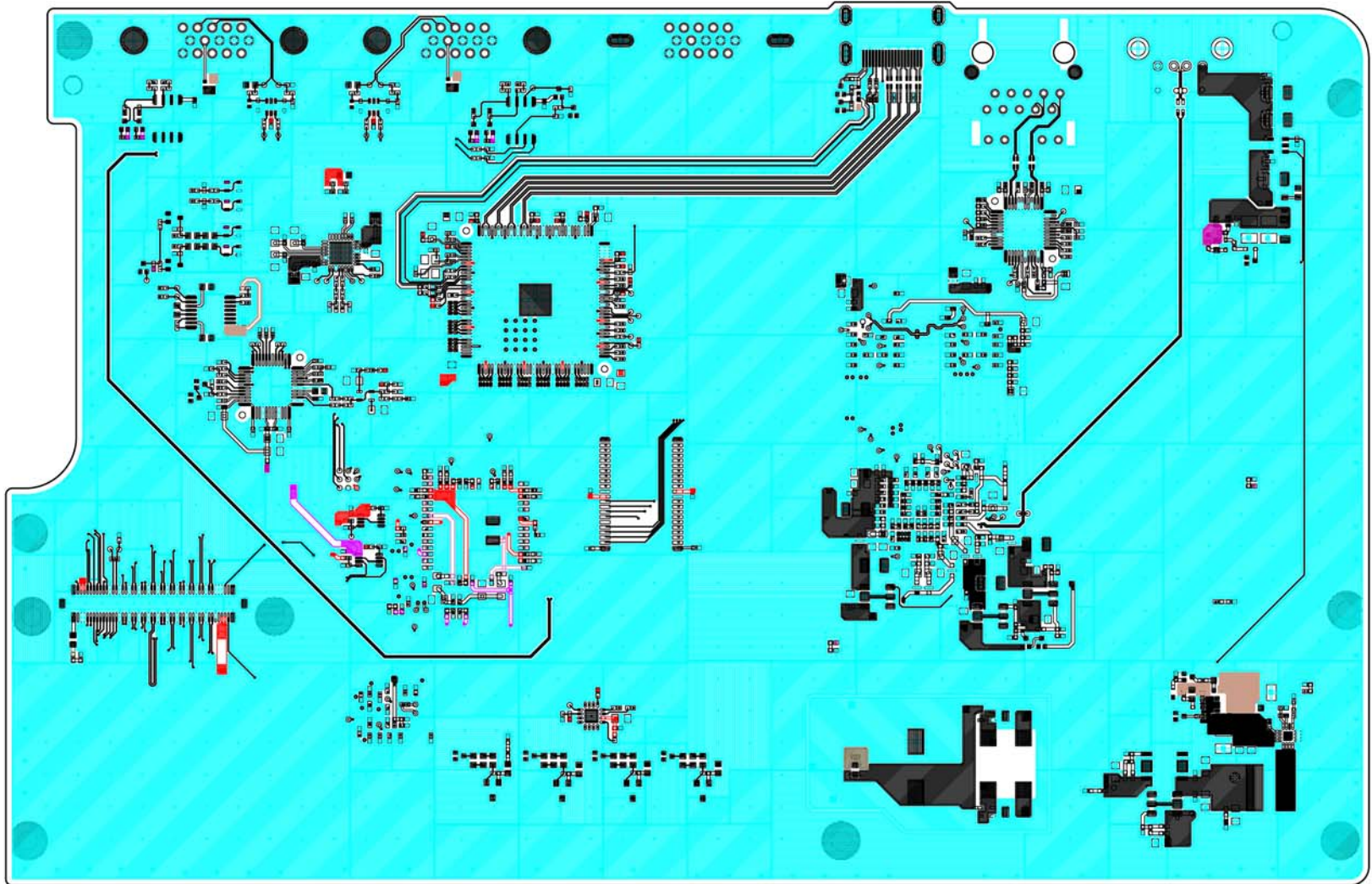
C936-A-1 (PP) LAYER1



C936-A-1(PP) L1-Assy'

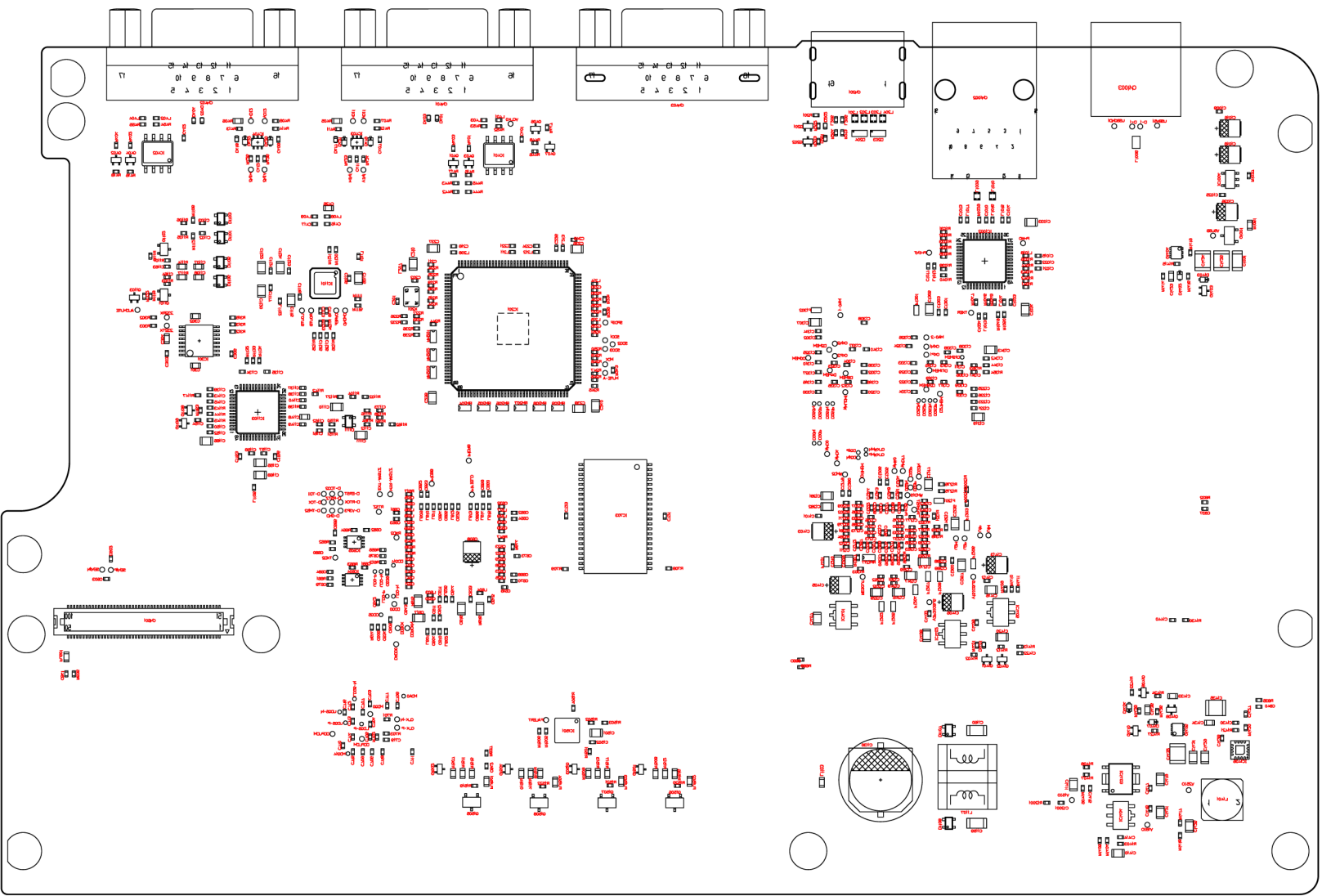


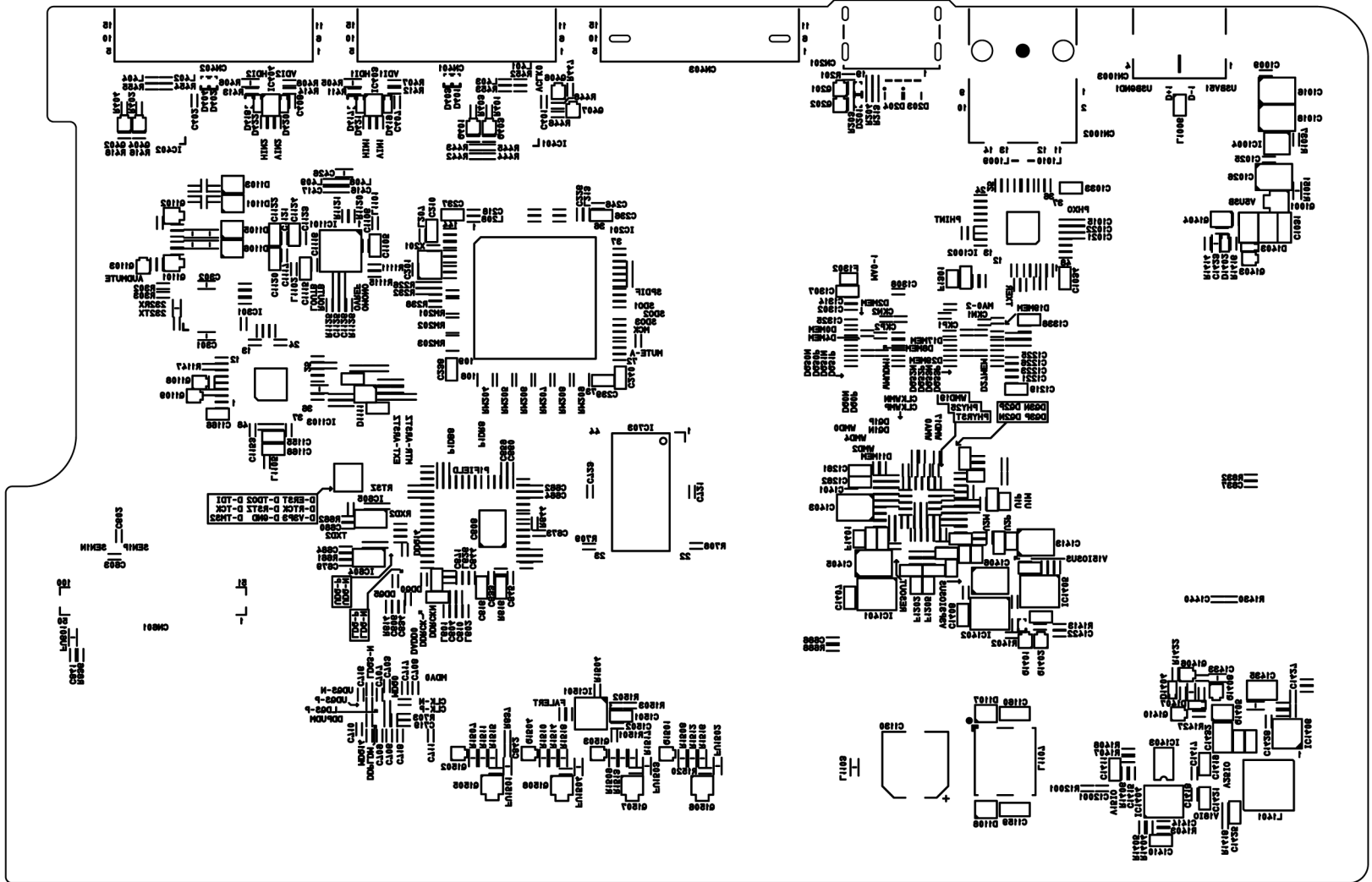
C936-A-1 (PP) LAYER1-SILK



C936-A-1 (PP) LAYER8

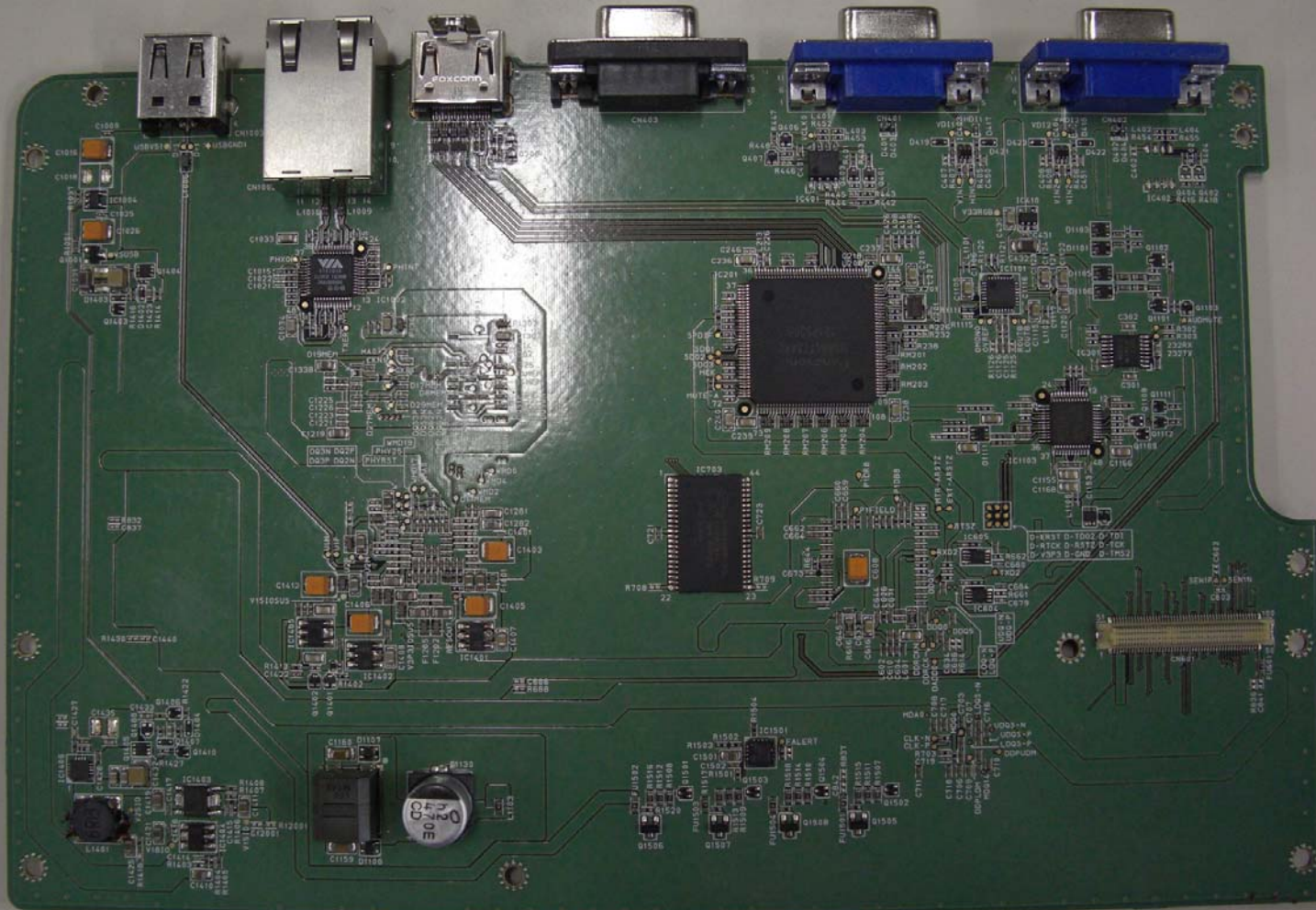
C93E-A-1(P) L8-Asy





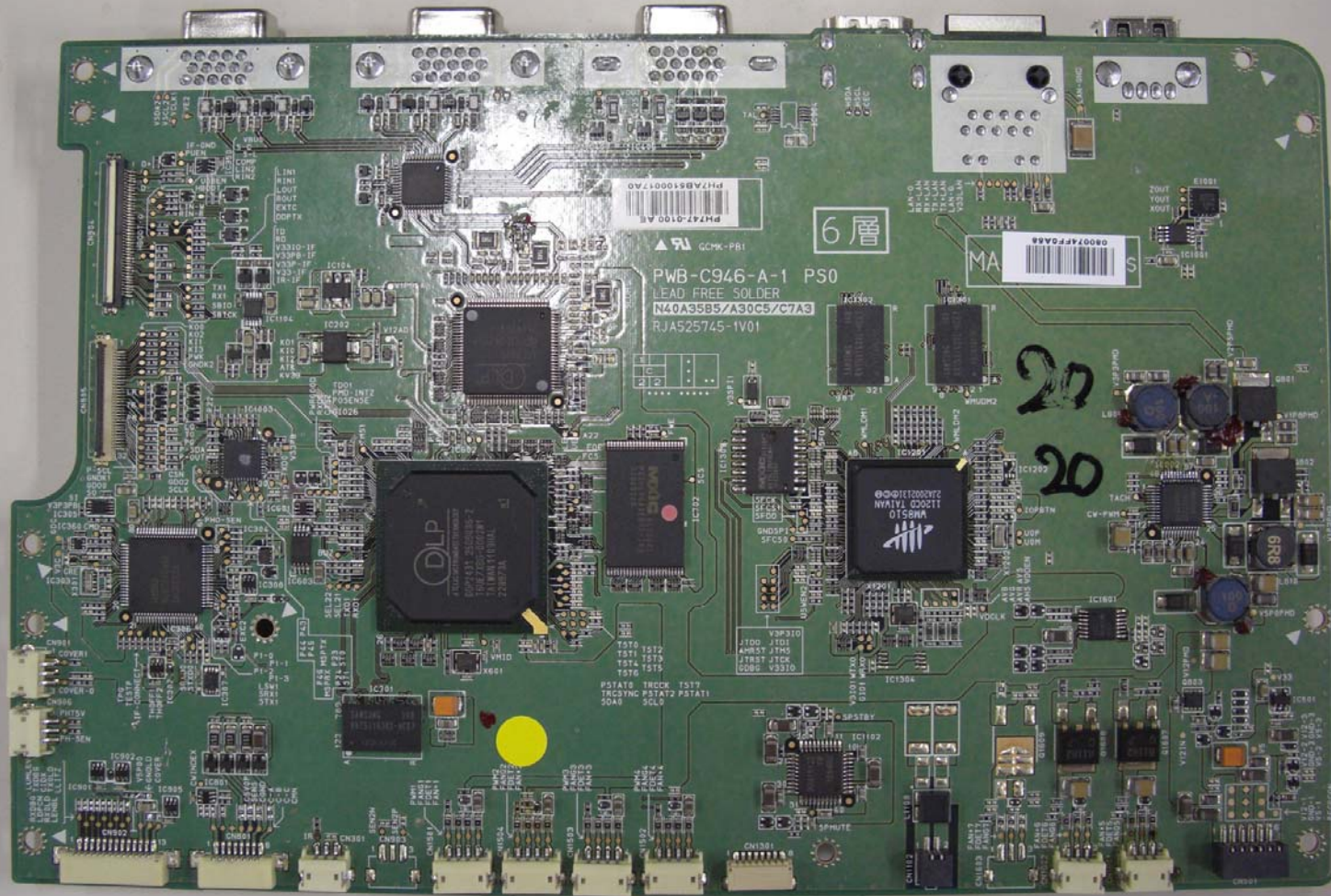
C936-A-1 (PP) LAYER8-SILK

Internal Photo

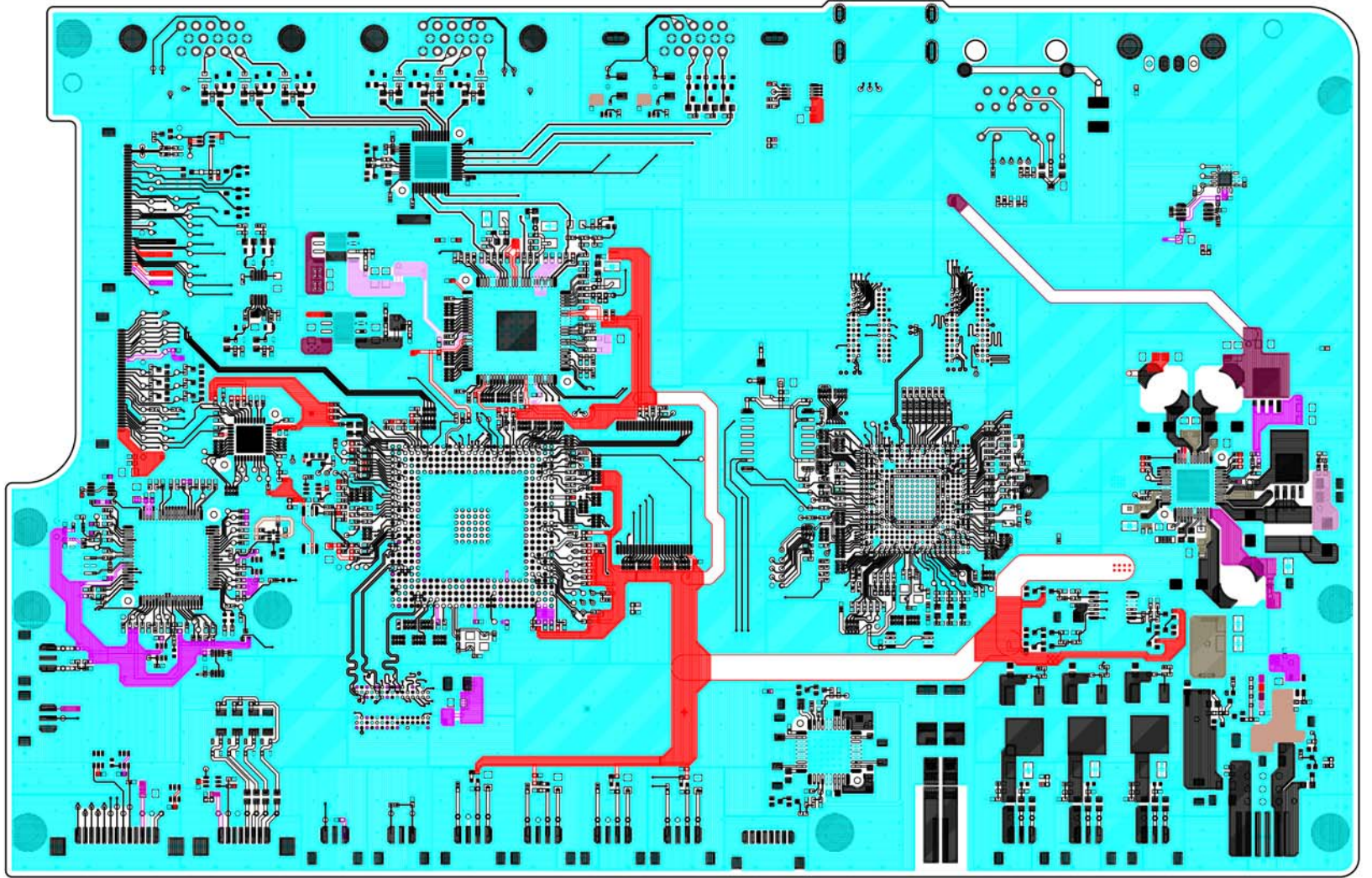


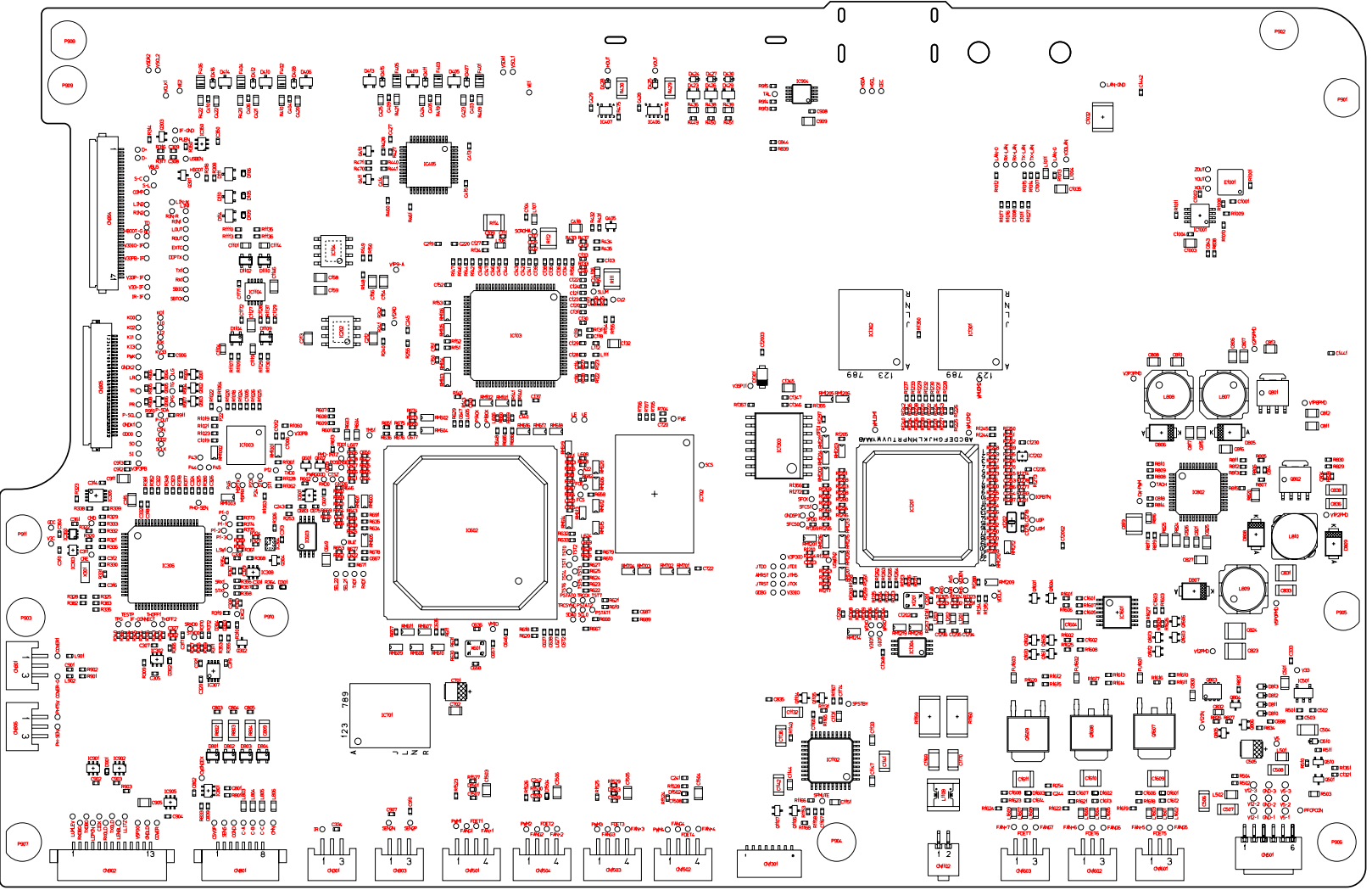
Main board(XJ-H2650) Upper After

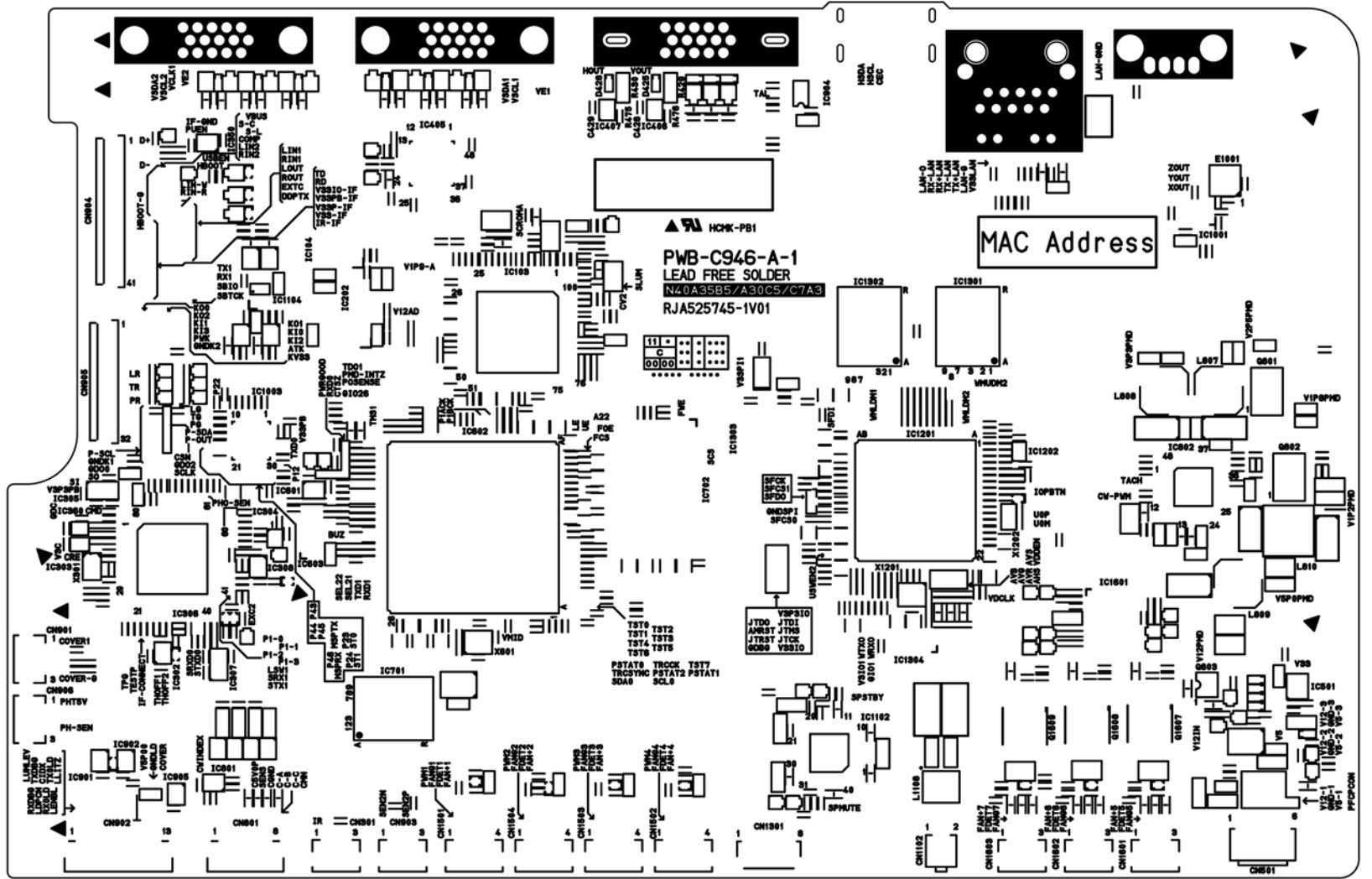
Internal Photo



Main board(XJ-H2650) Under After







▲ HCK-PB1
PWB-C946-A-1
LEAD FREE SOLDER
N40A3585/A30C5/C7A3
RJA525745-1V01

11	12	13	14	15	16	17	18	19	20
0	0	0	0	0	0	0	0	0	0
0	0	0	0	0	0	0	0	0	0

MAC Address

PCPCOM

